

(57) **Abrégé(suite)/Abstract(continued):**

a conductive filler in an amount sufficient to give an electrical resistivity below 550 ohms-meter and as an adhesion adjusting device an ethylene vinyl acetate, ethylene alkyl methacrylate copolymer having a molecular weight above 20,000 daltons and a polydispersity greater than 2.5 wherein the adhesion between the insulation and the semiconductive shield is between about 3-26 lbs per 1/2 inch.

